

CHIP, CHIP MANUFACTURING METHOD, COMPUTING DEVICE, AND SIGNAL TRANSMISSION METHOD

ABSTRACT

5 A chip, a chip manufacturing method, a computing device, and a signal transmission method are provided. A package substrate of the chip includes a basic pattern with six signal pins. A first pin, a second pin, a third pin, and a fourth pin in the six signal pins are sequentially spaced apart in a first direction, and a fifth pin and a sixth pin are spaced apart in a second direction. The fifth pin and the sixth pin are respectively located on two sides of a connection line between the second pin and the third pin. The first pin, the fourth pin, the fifth pin, and the sixth pin are data signal
10 pins, and the second pin and the third pin are control signal pins. In this solution, the data signal pins are respectively arranged at four extension ends of a cross-shaped pattern, the data signal pins are far away from each other, and each data signal pin has no adjacent data signal pin that may form a crosstalk source. In this way, electromagnetic crosstalk between pins can be effectively reduced. In addition, density of a pinmap can be improved, and a package area can be reduced.

15

FIG. 4